



# ECCOSORB® MF-LCP-115

## High Temperature, Magnetic Thermoplastic Absorber



### INJECTION MOLDABLE THERMOPLASTIC ABSORBER

MF-LCP-115 is a magnetic loaded injection moldable absorber grade based on Liquid Crystal Polymer (LCP). Benefit from LCP resin system, MF-LCP-115 has good high temperature resistance, high dimension stability and low coefficient of thermal expansion. Eccosorb MF-LCP series is an alternative of Eccosorb MF series for medium to high volume, 3D dimensional applications.

### FEATURES AND BENEFITS

- Injection moldable - ideal for complex shapes
- Cost effective for high volume
- Outstanding temperature stability
- RoHS compliant
- Halogen-free

### APPLICATIONS

- Telecom infrastructure and WLAN equipment
- High speed connectors
- Satellite communication
- Security and Defense

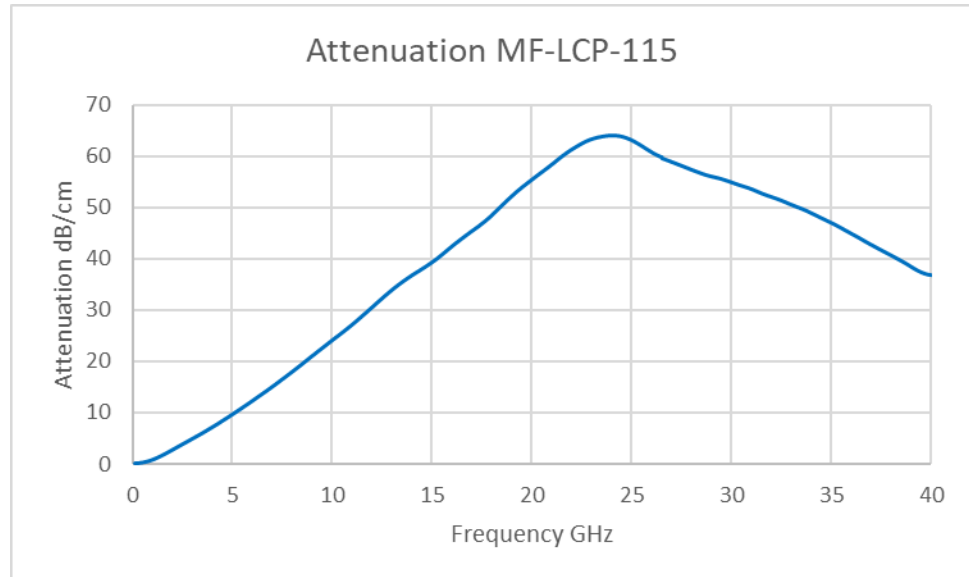
PROPERTIES	UNIT	TYPICAL VALUE
Color		Dark Grey
Operation Temperature	°C	-40 - 170
Volume resistivity	Ω/cm	>10 <sup>15</sup>
Tensile Strength	MPa	40
Tensile Elongation	%	0.5
Izod notched Impact strength	J/m	22
Flexural Strength		60
Flexural Modules		13
Heat Deflection Temperature	°C	190
CTE, Parallel to Flow	E-6/°C (20-150°C)	20
Transverse to Flow		70
UL Flammability		UL V0 Pending

\*Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to verify the material in application.

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### AVAILABILITY

- MF-LCP-115 is available as finished injection molded part according to customer's drawing. Please contact Laird local sales team for feasibility study
- Standard sample plaques available in flat surface at size 5mmX90mmx60mm

### RELATED PRODUCTS

- Laird has other injection moldable absorber grades available for different frequency range with different resin system. Please consult Laird local sales team or visit Laird website for more information.
- Available Grades includes
  - 6-40GHz MF-PP, MF-TPE, MF-PA, MF-PPS
  - 60GHz above JCP-PA, JCP-PP9, JCP-PBT 252



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